Presented at Workshop on "UV detectors and instruments", Toulouse 28-29 November 2018

QE of front side and back side thinned CMOS Image Sensors between 100 and 400nm

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#### **Presentation Outline**

Types of thinning to increase sensitivity

- Theory behind the need of an AR coating
- Obtained QE of various thinning types

VUV measurements

Take Home Message

#### **Device Selection and Definitions**

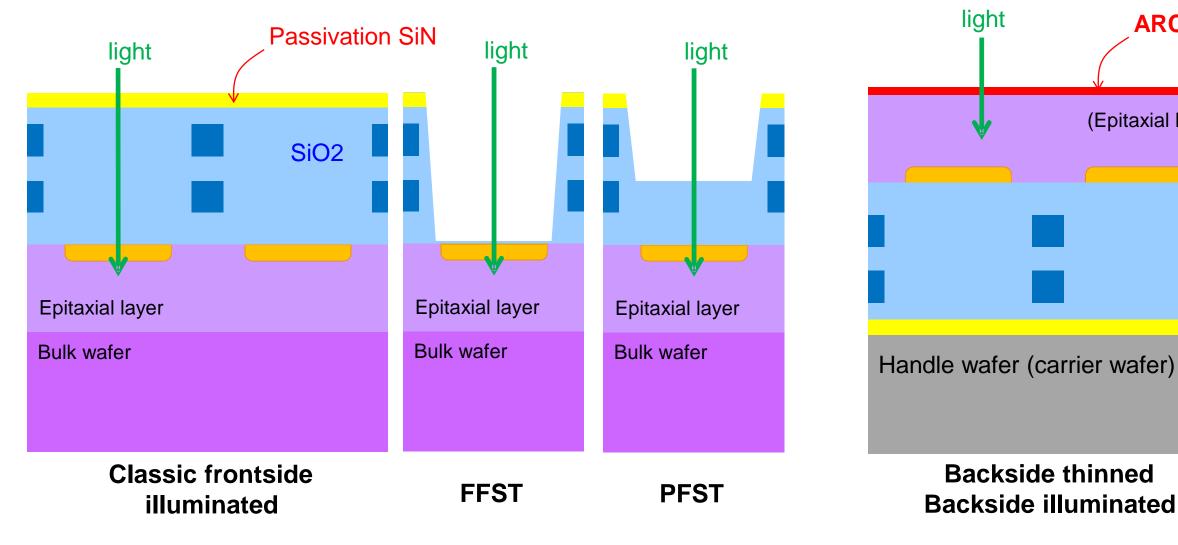
 All devices tested have nearly identical geometrical and operational parameters. Devices are processed at 3 different foundries/processes, in 110 and 180nm CIS nodes with various process options related to BSI, FST, ARC (anti-reflective coating) and wafer starting material

Name	Description
FSI	Classic frontside illuminated
FFST	Fully frontside thinned down to Silicon, apart from thin layer of SiO2
PFST	Partially frontside thinned: passivation removed, about half the SiO2 remaining
BSI	Backside illuminated, various ARC options, various epi-thickness and resistivity options

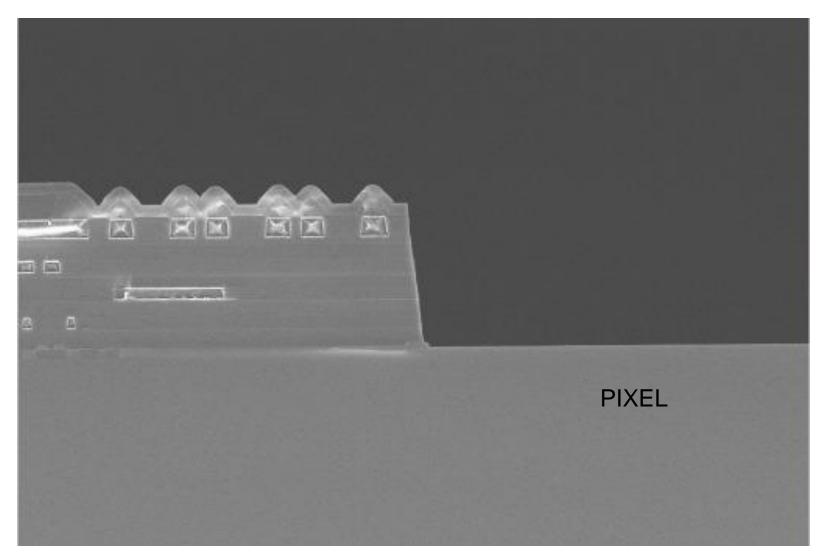
ARC

(Epitaxial layer)

#### Types of Thinning



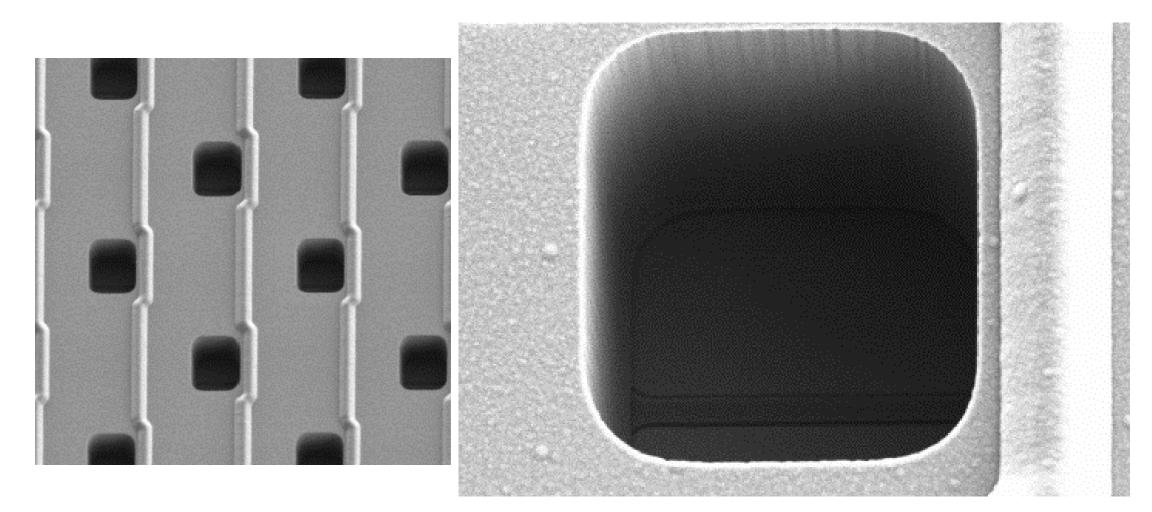
## Fully FST SEM cross section (device "d")



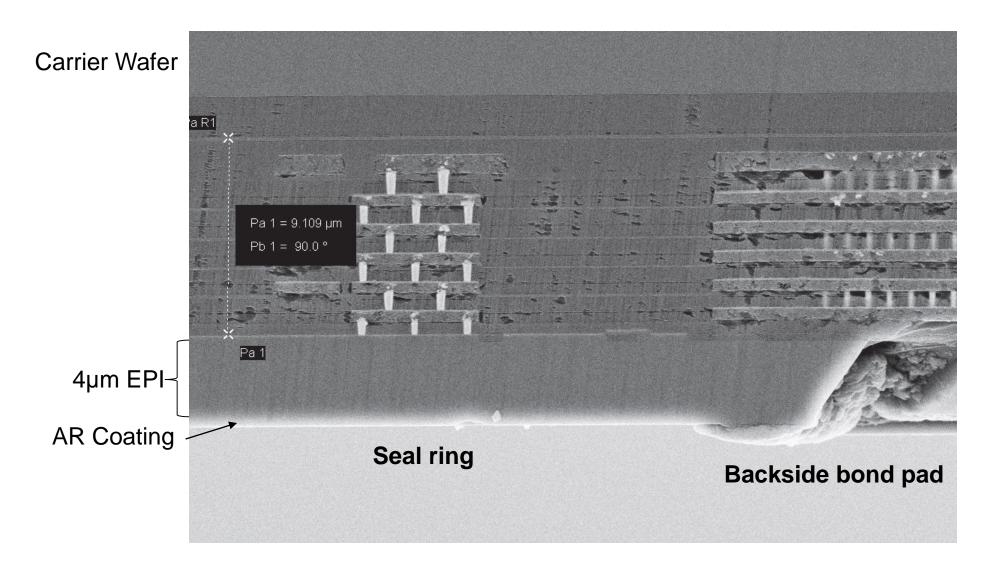
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## 2<sup>nd</sup> Fully FST example (device "BASTION") Caeleste



#### **Caeleste** BSI example SEM cross-section (device "R")

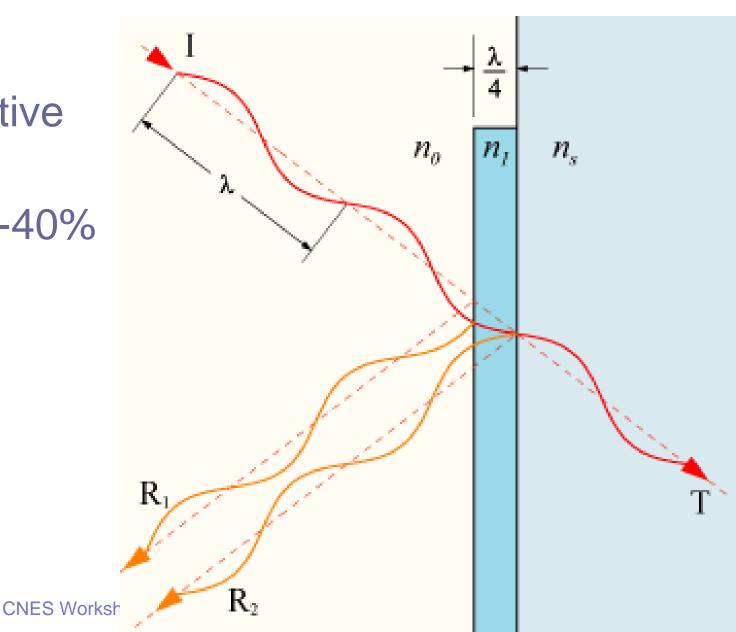


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#### Some Theory

- Silicon has high refractive index.
- Without Ar coating, 30-40% reflection.
- For UV, difficult to find CMOS compatible transparant materials



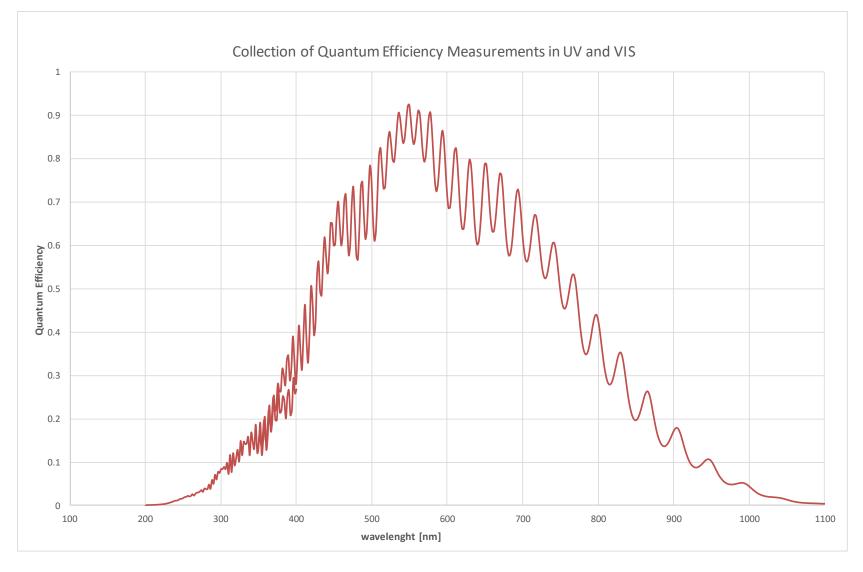
#### Anti reflection coating (ARC)

### Maximal QE is determined by reflection at air-Si interface ⇒ n<sub>Si</sub> ≈ 4 => huge reflection

- Adding a coating can reduce the reflection
- Single layer
  - ⇒ At a fixed wavelength, perpendicular reflection can be removed by a simple single layer coating

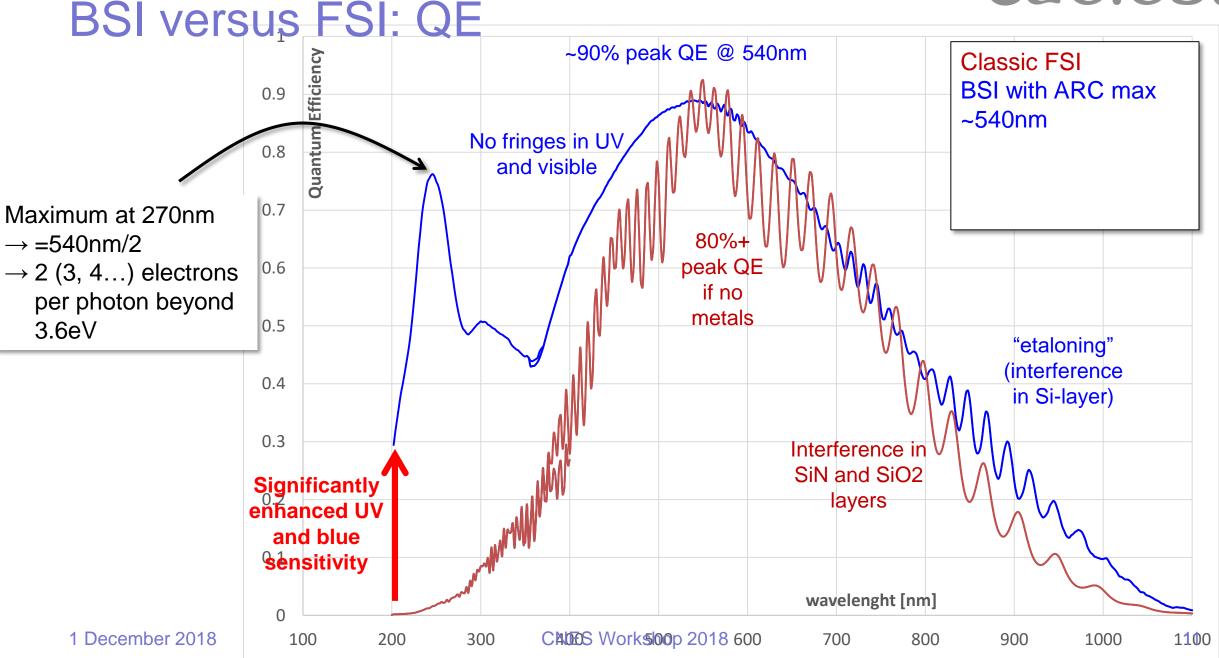
- $n_{ARC} = sqrt(n1*n2)$
- $d_{ARC} = \lambda/(4*n_{ARC})$
- $\Rightarrow$  Still reflection at other wavelengths, other angles
- Multiple layers
  - $\Rightarrow$  Reflection can be minimized across a range of wavelengths and angles
  - $\Rightarrow$  Better performance if layers with different refractive indices (n1 < n < n2) are available

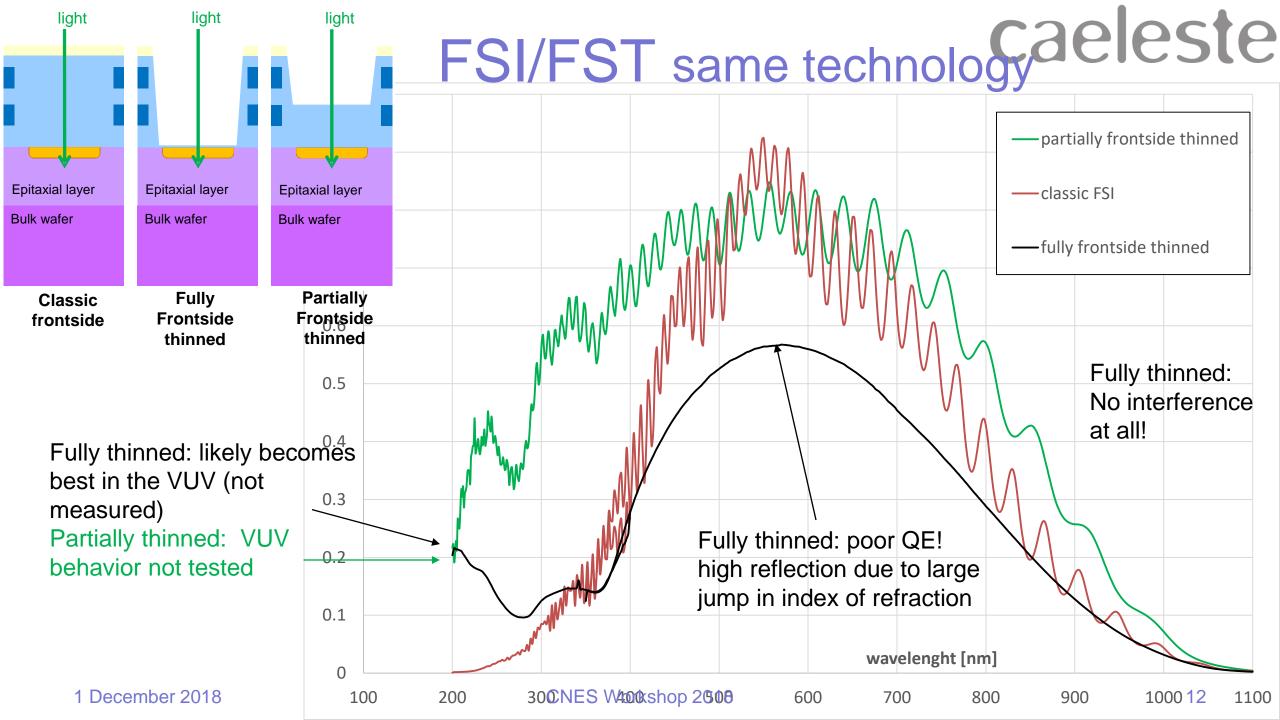
#### QE of standard FSI



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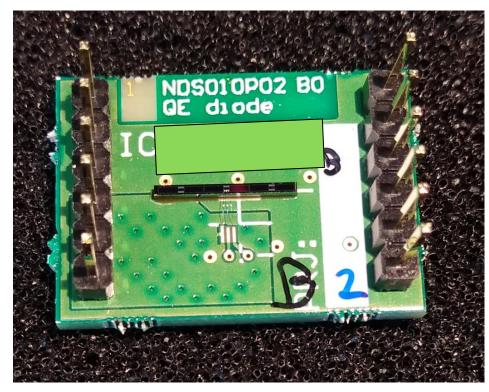




#### **VUV** measurements

- 200-1100nm done at Caeleste
- 100-200nm (VUV) at PTB in Berlin
  - Mandatory to do testing in Vacuum.
- UV beam can cause secondary emission which will influence QE results. Shielding required.

#### VuV measurements - Setup



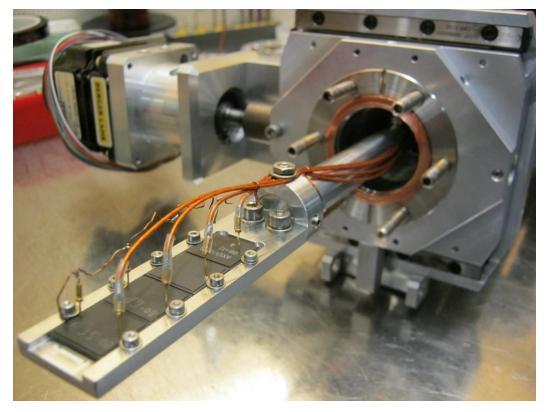
Caeleste QE test Structures 3 bondwires

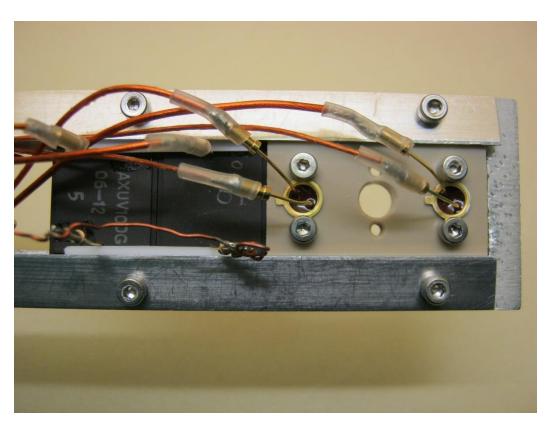




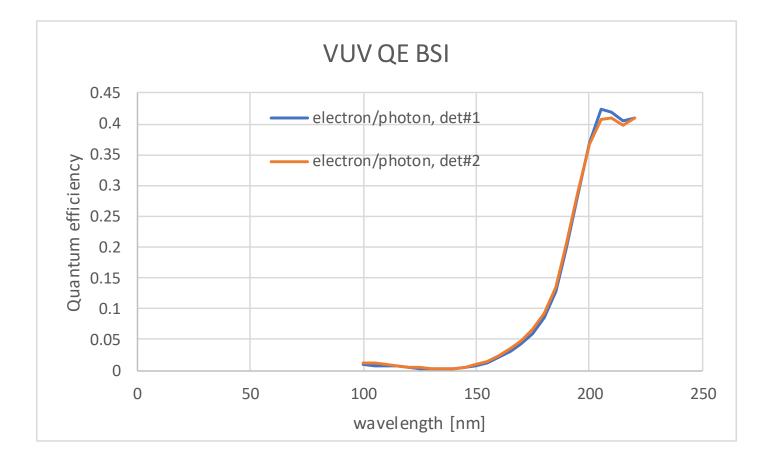
PEEK holder with pin hole above the pixel area

#### Test Setup at PTB



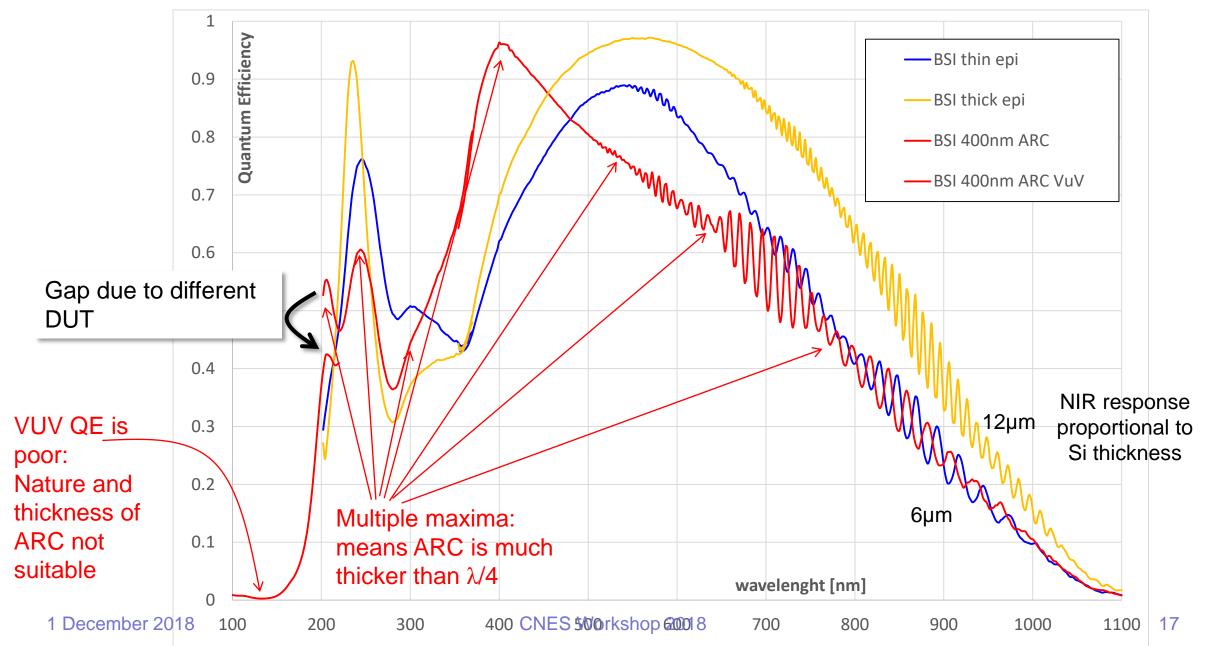


#### **VuV Measurements Results**

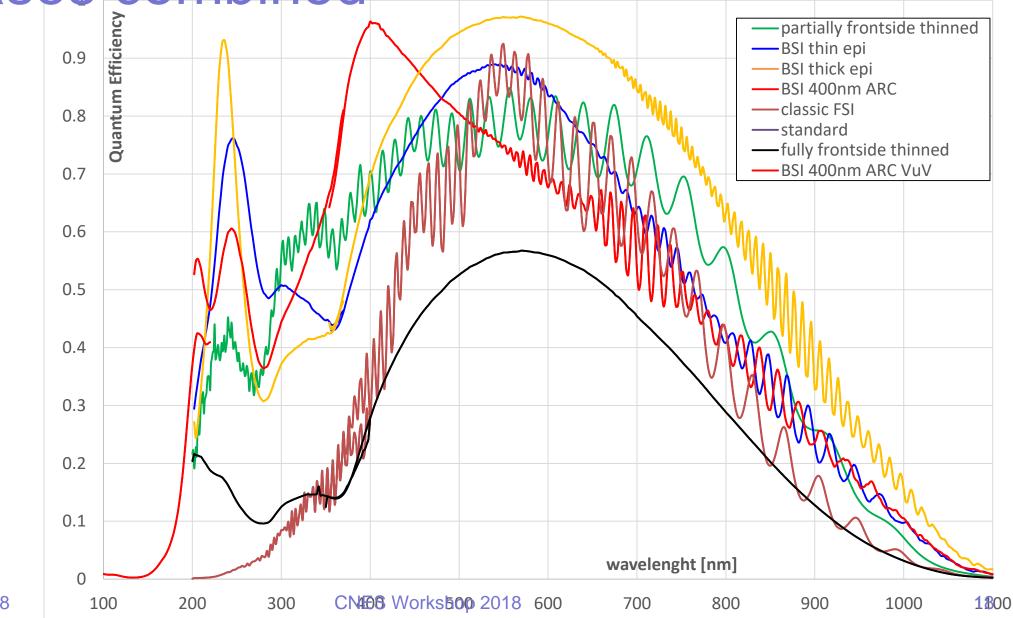


- Thickness of AR coating has a significant impact on the QE performance.
- Thickness of AR coating = 160nm
- Future measurements planned with thinner AR stack and other AR compositions which are more transparant to UV.

#### **BSI** cases - combined



#### All cases combined



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#### Take home messages

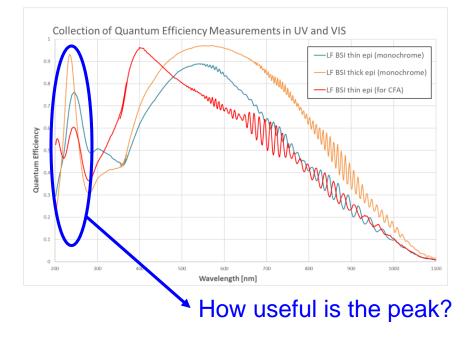
- Largest UV sensitivity killer: SiN passivation. BSI or FST are solutions.
- If you want absolutely no interference fringes: fully FST
- If you do not want interference fringes in the UV → green: BSI
- Partial FST yields decent QEs 200-400nm, yet suffers form interference fringes
- Chemical nature and thickness of ARC and Si impacts UV QE
- QE peaks are seen at fractions of ARC wavelength optimum



#### Questions

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#### UV peak at 250nm?



- One high energy photon/particle generates a number of e-h pairs
- QE can actually be higher than 100%
- Generation time of e-h pairs no longer random
- Formula of photon shot noise as square root of e-h pairs no longer valid
- Noise will be higher than sqrt(N), excess noise due to non-Poisson distribution
- Peak not very useful